# IRF9Z14

Vishay Siliconix



**TO-220AB** 

**PRODUCT SUMMARY** 

V<sub>DS</sub> (V)

R<sub>DS(on)</sub> (Ω)

Q<sub>qs</sub> (nC)

Q<sub>gd</sub> (nC)

Q<sub>q</sub> max. (nC)

Configuration

G C

 $V_{GS} = -10 V$ 

P-Channel MOSFET

0.50

-60

12

3.8

5.1

Single

# **Power MOSFET**

## FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

#### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

### DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9Z14PbF
Lead (Pb)-free and halogen-free	IRF9Z14PbF-BE3

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>	= 25 °C, unl	ess otherwis	e noted)			
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage		V <sub>DS</sub>	-60	N		
Gate-source voltage		V <sub>GS</sub>	± 20	V		
Continuous drain current	V <sub>GS</sub> at 10 V	$T_{C} = 25 \text{ °C}$ $T_{C} = 100 \text{ °C}$	I <sub>D</sub>	-6.7		
Continuous drain current	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		-4.7	А	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	-27		
Linear derating factor			0.29	W/°C		
Single pulse avalanche energy <sup>b</sup>		E <sub>AS</sub>	140	mJ		
Repetitive avalanche current <sup>a</sup>		I <sub>AR</sub>	-6.7	A		
Repetitive avalanche energy <sup>a</sup>		E <sub>AR</sub>	4.3	mJ		
Maximum power dissipation	T <sub>C</sub> = 25 °C		PD	43	W	
Peak diode recovery dV/dt <sup>c</sup>		dV/dt	-4.5	V/ns		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175			
Soldering recommendations (peak temperature) <sup>d</sup>	For 10 s			300	°C	
Mounting torque	6-32 or M3 screw			10	lbf ∙ in	
Mounting torque				1.1	N · m	

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b.  $V_{DD} = -25 \text{ V}$ , starting  $T_J = 25 \text{ °C}$ , L = 3.6 mH,  $R_g = 25 \Omega$ ,  $I_{AS} = -6.7 \text{ A}$  (see fig. 12)

c.  $I_{SD} \leq$  -6.7 A, dl/dt  $\leq$  90 A/µs,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq$  175 °C

d. 1.6 mm from case

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THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R <sub>thJA</sub>	-		62				
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50 - - 3.5			°C/W			
Maximum junction-to-case (drain)	R <sub>thJC</sub>							
<b>SPECIFICATIONS</b> ( $T_J = 25 \text{ °C}$ , u	unless otherw	ise noted)						
PARAMETER	SYMBOL		CONDITI	ONS	MIN.	TYP.	MAX.	UNIT
Static							L	I
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0$	) V, I <sub>D</sub> = -2	250 μA	-60	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I	<sub>D</sub> = -1 mA	-	-0.060	-	V/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>		ν <sub>GS</sub> , I <sub>D</sub> = -2		-2.0	-	-4.0	V
Gate-source leakage	I <sub>GSS</sub>		$a_{\rm S} = \pm 20$		-	-	± 100	nA
			60 V, V <sub>GS</sub>		-	-	-100	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -48 V, V			-	-	-500	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	1	= -4.0 A <sup>b</sup>	-	-	0.50	Ω
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> = -2	25 V, I <sub>D</sub> = -	-4.0 A <sup>b</sup>	1.4	-	-	S
Dynamic						•	1	
Input capacitance	C <sub>iss</sub>	\ \	$l_{\alpha\alpha} = 0.1/$		-	270	-	
Output capacitance	C <sub>oss</sub>	$v_{GS} = 0 v,$		170	-	pF		
Reverse transfer capacitance	C <sub>rss</sub>			-	31	-		
Total gate charge	Qg				-	-	12	nC
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = -10 V		A, $V_{DS} = -48 V$ ,	-	-	3.8	
Gate-drain charge	Q <sub>gd</sub>	-	see ng	g. 6 and 13 <sup>b</sup>	-	-	5.1	
Turn-on delay time	t <sub>d(on)</sub>				-	11	-	
Rise time	tr	- Vpp = -:	30 V, I <sub>D</sub> =	-6.7 A	-	63	-	ns
Turn-off delay time	t <sub>d(off)</sub>	$R_g = 24 \Omega, R_f$			-	10	-	
Fall time	t <sub>f</sub>	-			-	31	-	
Gate input resistance	R <sub>g</sub>	f = 1 MHz, open drain		1.4	-	8.7	Ω	
Internal drain inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	- nH	
Internal source inductance	L <sub>S</sub>			-	7.5	-		
Drain-Source Body Diode Characteristi	cs							
Continuous source-drain diode current	۱ <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-6.7	A			
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>			-	-	-27		
Body diode voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>s</sub>	<sub>6</sub> = -6.7 A,	$V_{GS}$ = 0 V <sup>b</sup>	-	-	-5.5	V
Body diode reverse recovery time	t <sub>rr</sub>	T 05 %0 1	674 -11	dt 100 4 ( b	-	80	160	ns
Body diode reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = -	-o.1 A, dl/	$a_i = 100 \text{ A/}\mu\text{s}^{-1}$	-	0.096	0.19	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic turr	n-on time i	s negligible (turn	-on is do	minated b	y L <sub>S</sub> and	L <sub>D</sub> )

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)

b. Pulse width  $\leq$  300 µs; duty cycle  $\leq$  2 %

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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

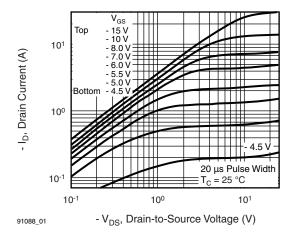


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

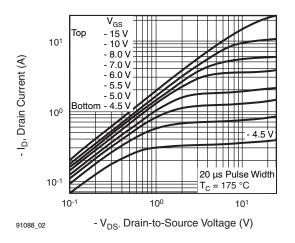


Fig. 2 - Typical Output Characteristics,  $T_C$  = 175  $^\circ$  C

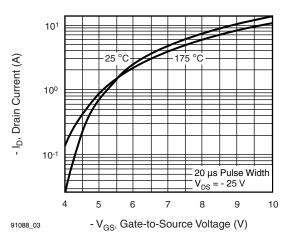


Fig. 3 - Typical Transfer Characteristics

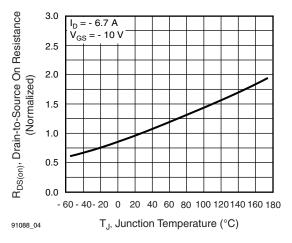


Fig. 4 - Normalized On-Resistance vs. Temperature

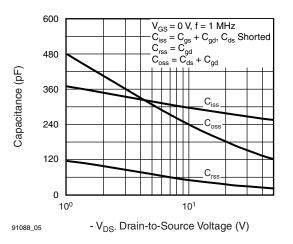


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

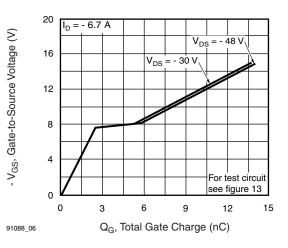


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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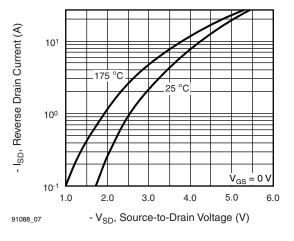


Fig. 7 - Typical Source-Drain Diode Forward Voltage

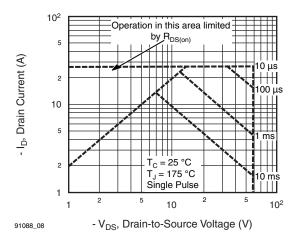


Fig. 8 - Maximum Safe Operating Area

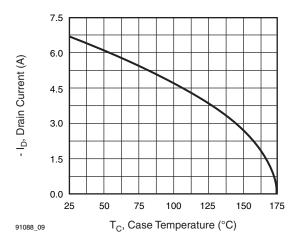


Fig. 9 - Maximum Drain Current vs. Case Temperature

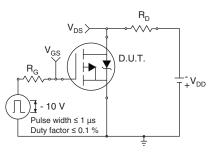


Fig. 10a - Switching Time Test Circuit

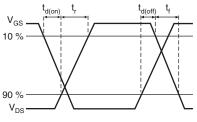
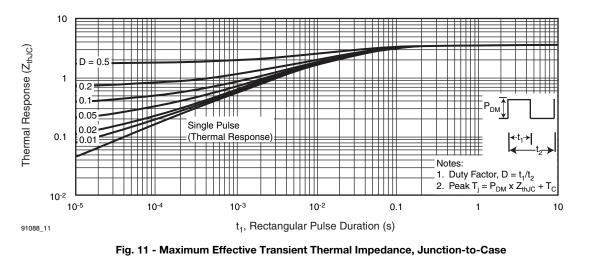


Fig. 10b - Switching Time Waveforms



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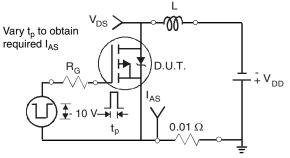


Fig. 12a - Unclamped Inductive Test Circuit

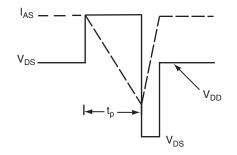


Fig. 12b - Unclamped Inductive Waveforms

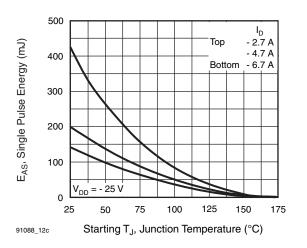


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

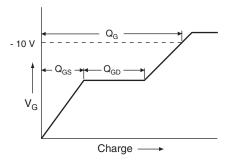


Fig. 13a - Basic Gate Charge Waveform

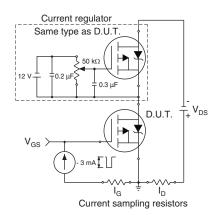
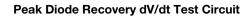


Fig. 13b - Gate Charge Test Circuit





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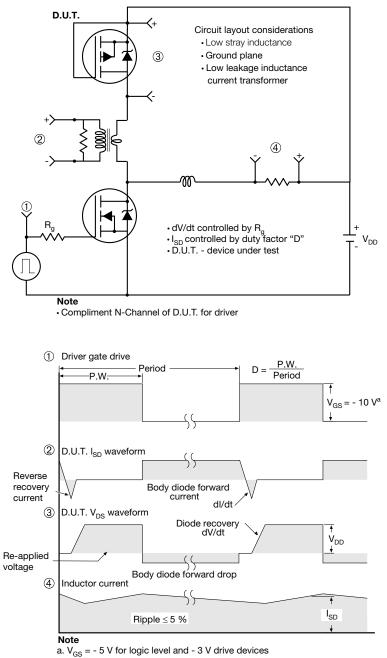


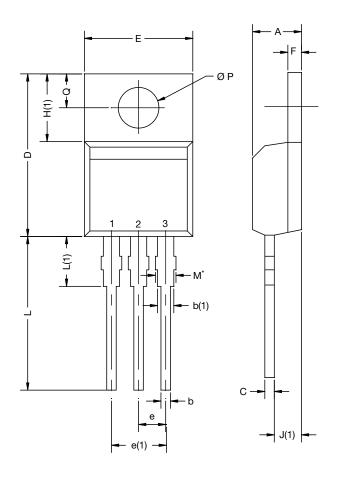
Fig. 14 - For P-Channel

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TO-220-1



DIM	MILLIN	METERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØP	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

### Note

• M\* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

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